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New Manual Wire Bonder Series 53xx

F&K Delvotec Semiconductor GmbH, Braunau, Austria, completes the product range: The new series 53xx of manual wire bonders is intended for first time users those with a limited budget. Potential users include research institutes, laboratories and manufacturers of small series of commercial applications. Two variants are available for Au Ball/Wedge and Au/Al Wedge/Wedge bonding. The bonding heads and bond tools can be easily exchanged. A motorised 90°-Z-axis and an LCD display for programming in Windows standard with a hard disk complete the bonder. A shuttle wheel and a push-button actuator control the operation and very simple programming. The loop forms and most important bond parameters can be adjusted and stored within a very short time. A motor drive produces a controlled, programmable tail length. No complex, mechanical adjustments are necessary as a result of the consequently simple mechanical structure. All common wires/ribbon can be processed, a variety of microscopes and work holders is available. Printers are connected via USB.



F&K Delvotec's new manual wire bonder series 53xx